



MULTI-FUN

ENABLING MULTI-FUNCTIONAL
PERFORMANCE THROUGH
MULTI-MATERIAL ADDITIVE
MANUFACTURING



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Investigations into the robustness of additively manufactured, embedded electrical conductors

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Metal Additive Manufacturing Conference (MAMC)

<https://www.mamc2022.org/>

www.multi-fun.eu



Outline



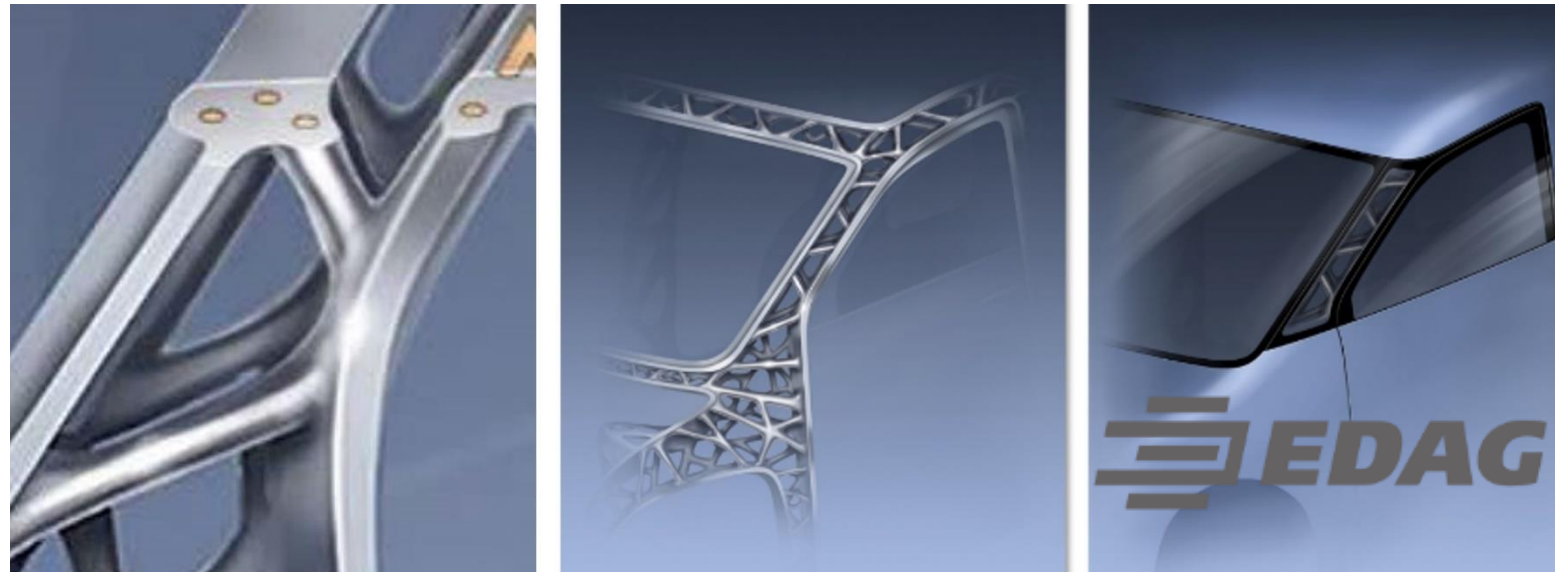
- ❑ Motivation & Challenge
- ❑ What has happened so far short reminder to
 - Deposition of conductive & insulating layers
 - Functional integration into light metals by WAAM
- ❑ Robustness during manufacturing
- ❑ Robustness during mechanical testing
- ❑ Conclusions & Outlook
- ❑ Acknowledgments



Motivation for investigation about the integration of electrical conductors into light metal components

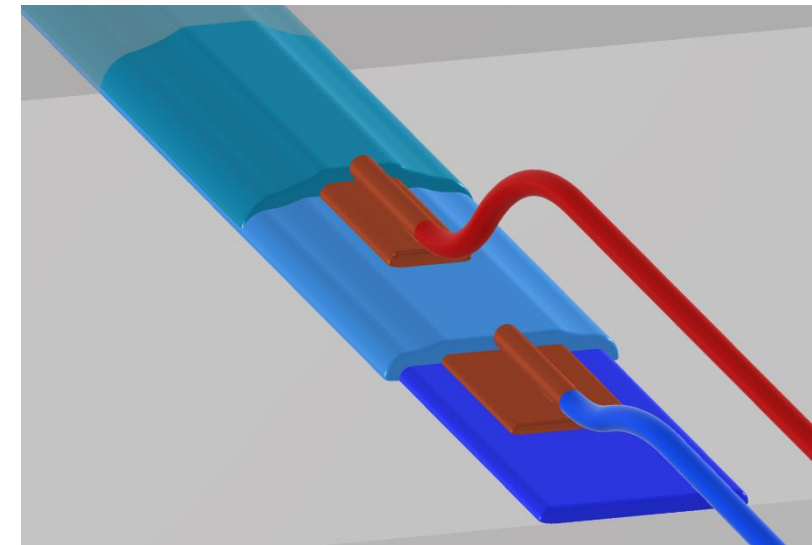
- Enabling new designs
- Exploiting novel DED technologies
- Demonstrating multi-material manufacturing opportunities

Example: MULTI-FUN Demonstrator, designed by EDAG:
“See-through A-pillar”



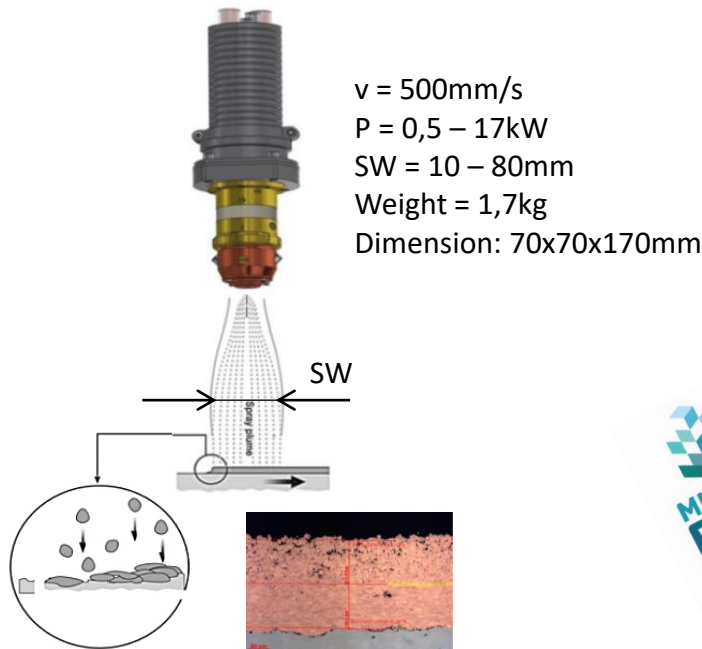
Main challenges of integrating metal conductors into metal components by DED

- Introducing insulator materials separating metal conductors from structural metal
- Focussing on DED technologies for automated 3D manufacturability
- Connecting integrated copper tracks with other cabling
- **Robust processing**
- **Automation of all processes**

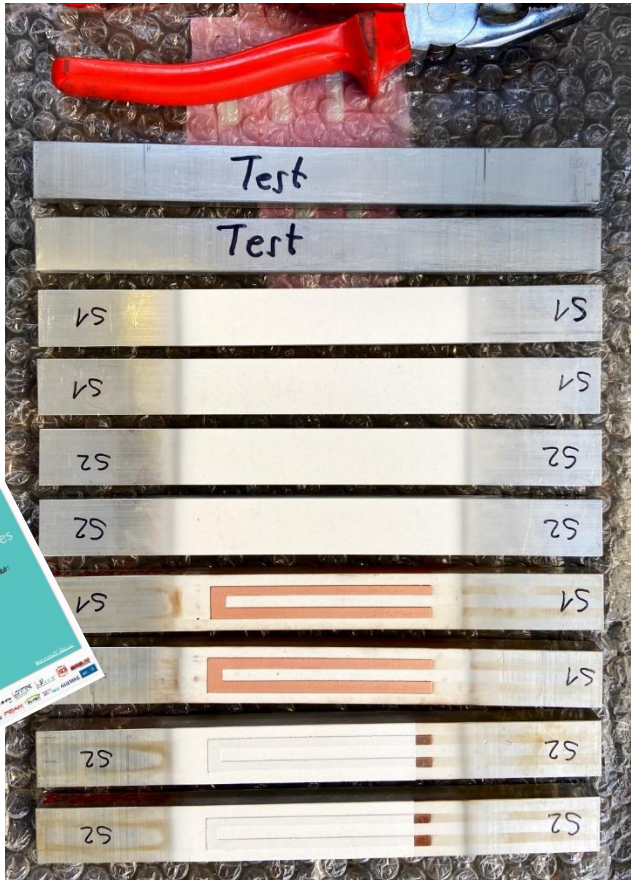


Layer deposition by INOCON's InoCoat technology ("APPD")

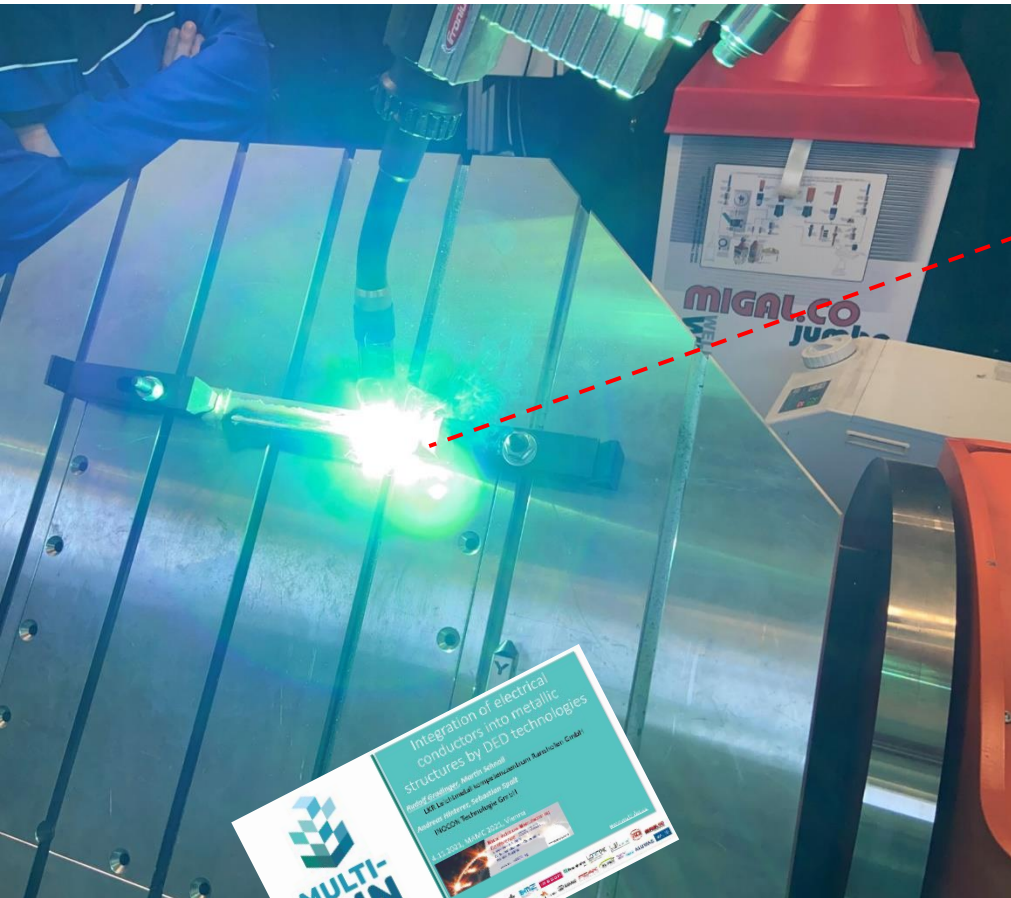
Deposition of electrical insulation & conductive layers onto metal parts by APPD (APPD=atmospheric pressure plasma deposition)



Source: Heimann, Plasma spray coating (2008)



Embedding the conductor/insulator stack by WAAM



Next step: _____

Aluminium layers by WAAM

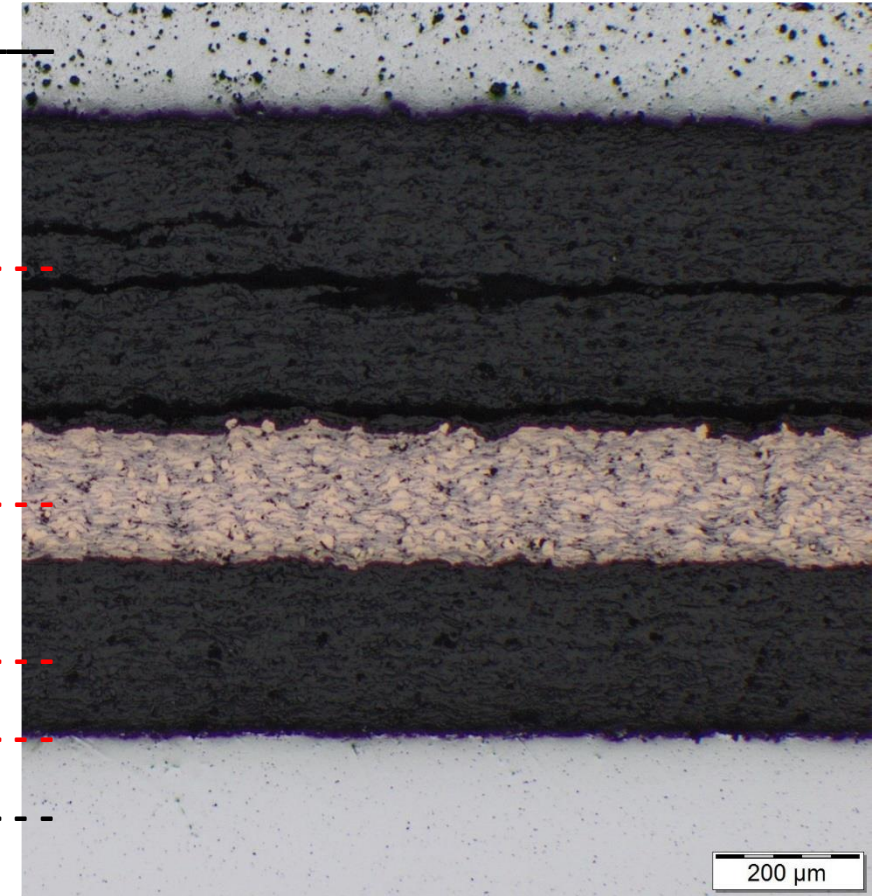
Al₂O₃ insulation layers - - -

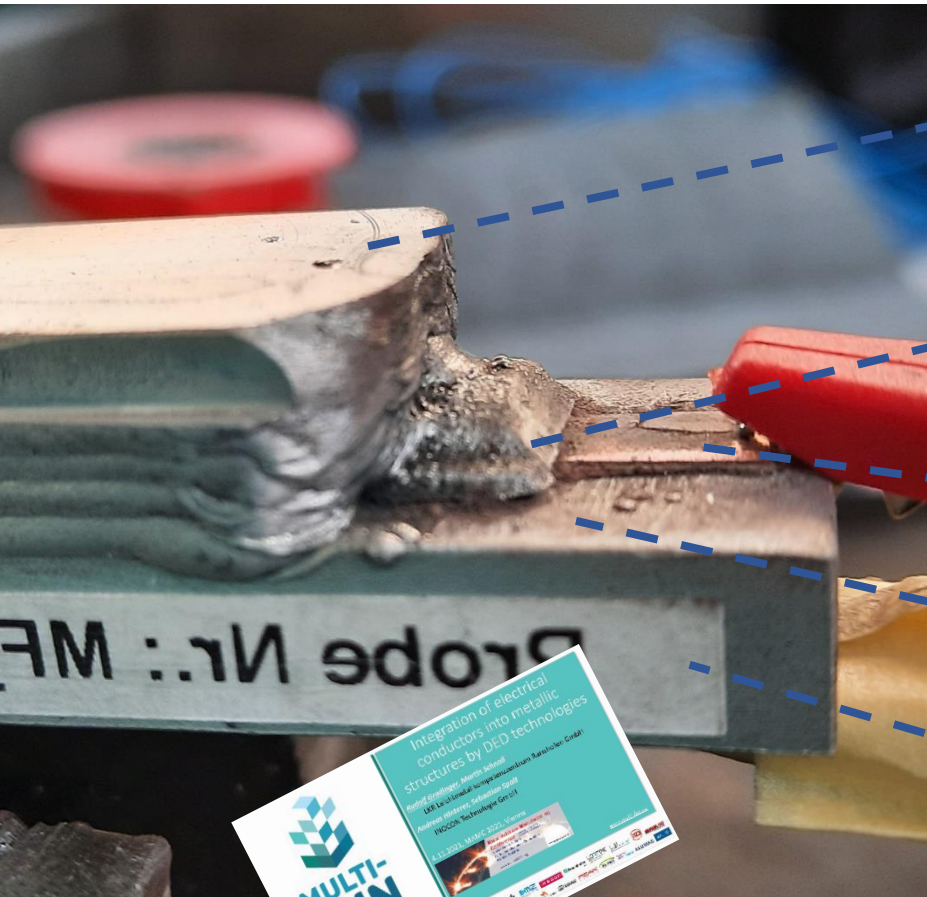
Cu electr. conductive layers - - -

Al₂O₃ insulation layers - - -

Surface treatment - - -

Aluminium substrate - - -





Next step: _____

Aluminium layers by WAAM

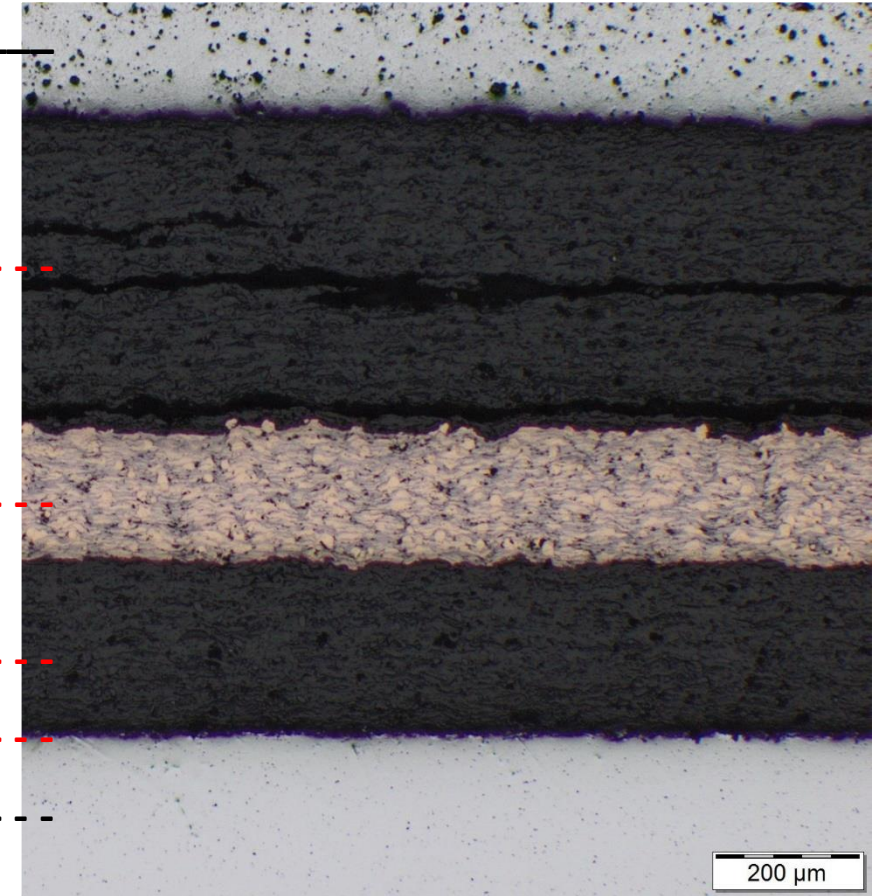
Al₂O₃ insulation layers - - -

- Cu electr. conductive layers - -

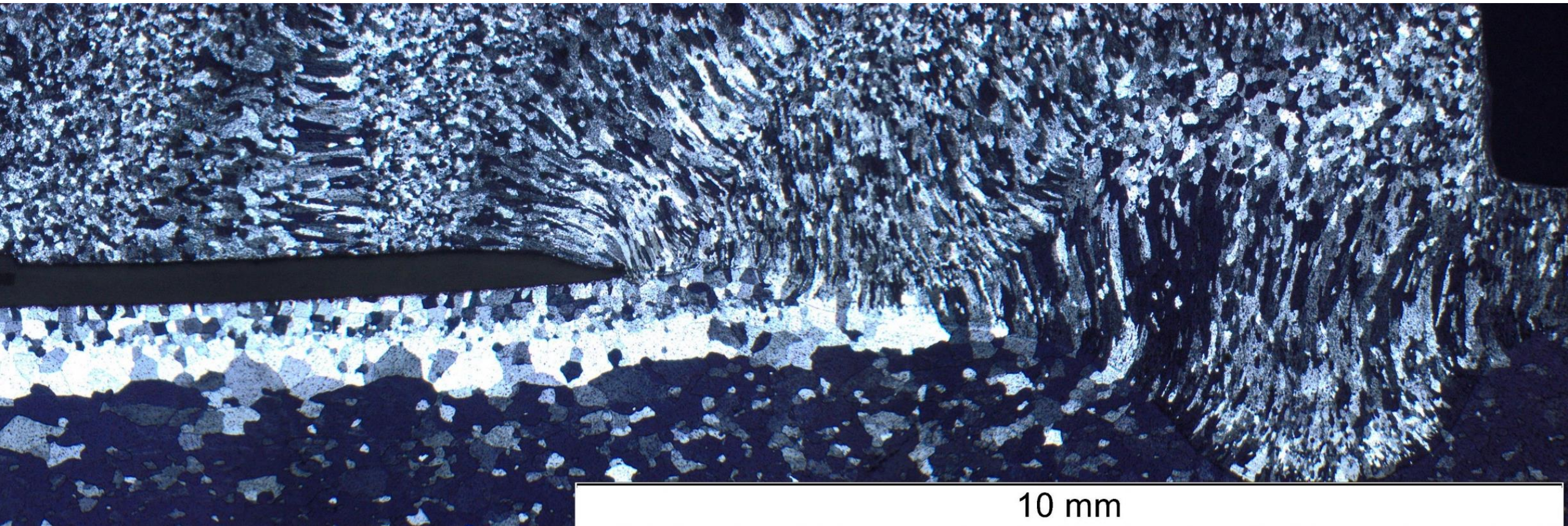
- Al₂O₃ insulation layers - -

Surface treatment - -

Aluminium substrate - -

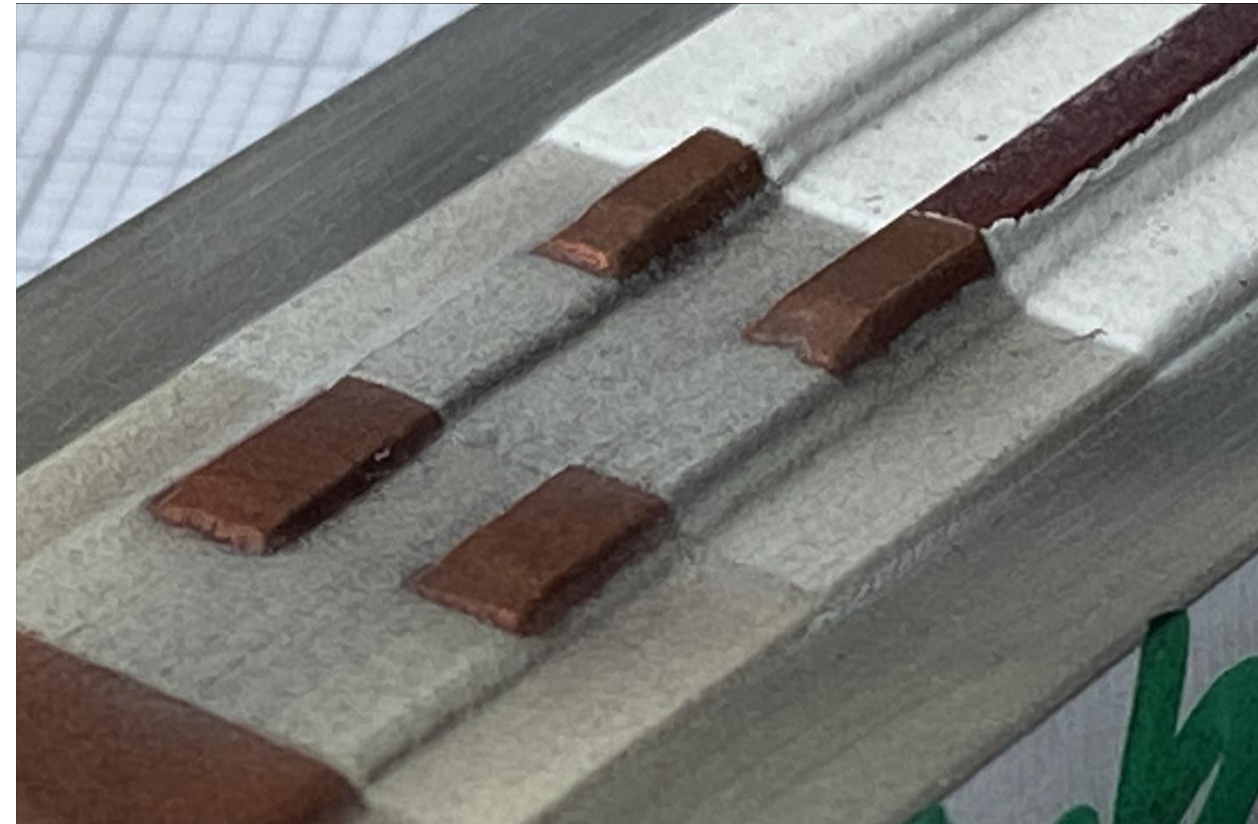


Embedding the conductor/insulator stack by WAAM (3)



Robustness during manufacturing

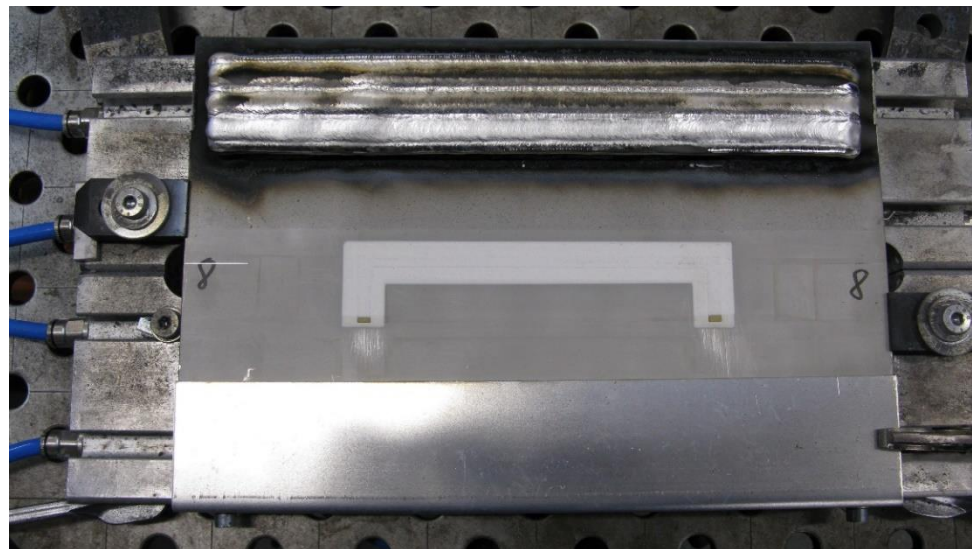
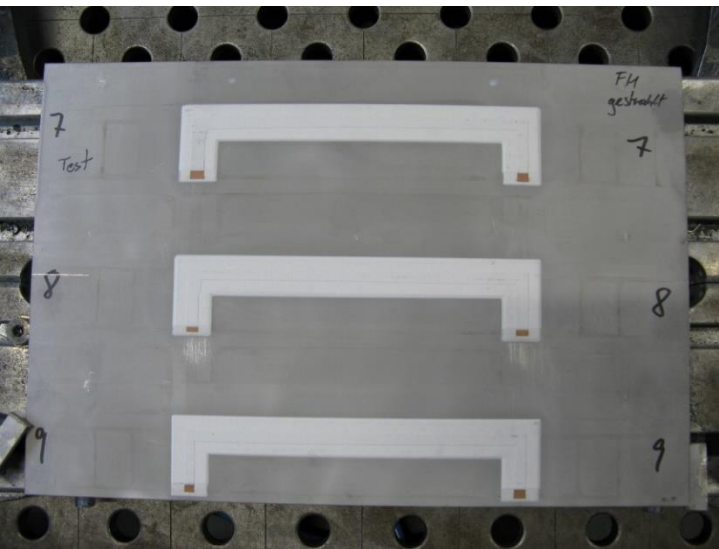
- Proper surface treatment of the metal substrate before applying APPD
- Following general thermal spraying process recommendations, esp. no sharp edges & corners of both the surfaces as well as the layer stack
- Apply proper masking to avoid unfavourable effects caused by overspray



▲ *5 insulated conductive layers*

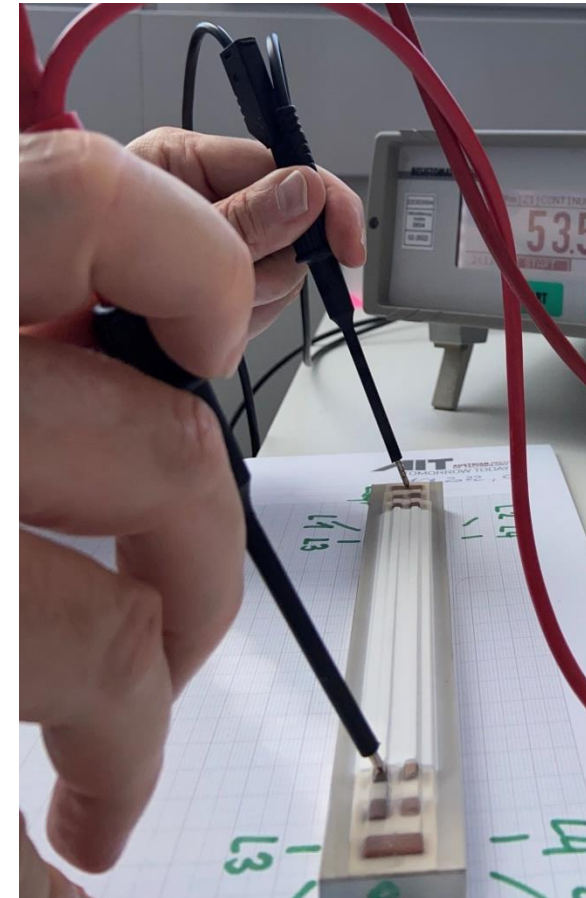
Robustness during manufacturing (2)

- Adapt the WAAM strategy for non-conductive substrate when applying transferred arc
- Avoid high distortion of the substrate during WAAM (otherwise the layered stack will debond or break)



Robustness during manufacturing (3)

- No influence of the WAAM process to the electrical resistance of the Copper stack (resulting values scatter lower than the scatter from manual measurements)
- No influence of the WAAM process to the insulation properties of the ceramic stacks (unless no breakage occurs at the end of the stacks)
- Debonding of stacks does not lead immediately to loss of conductivity
- Weld fume does not harm the values of manual electr. testing

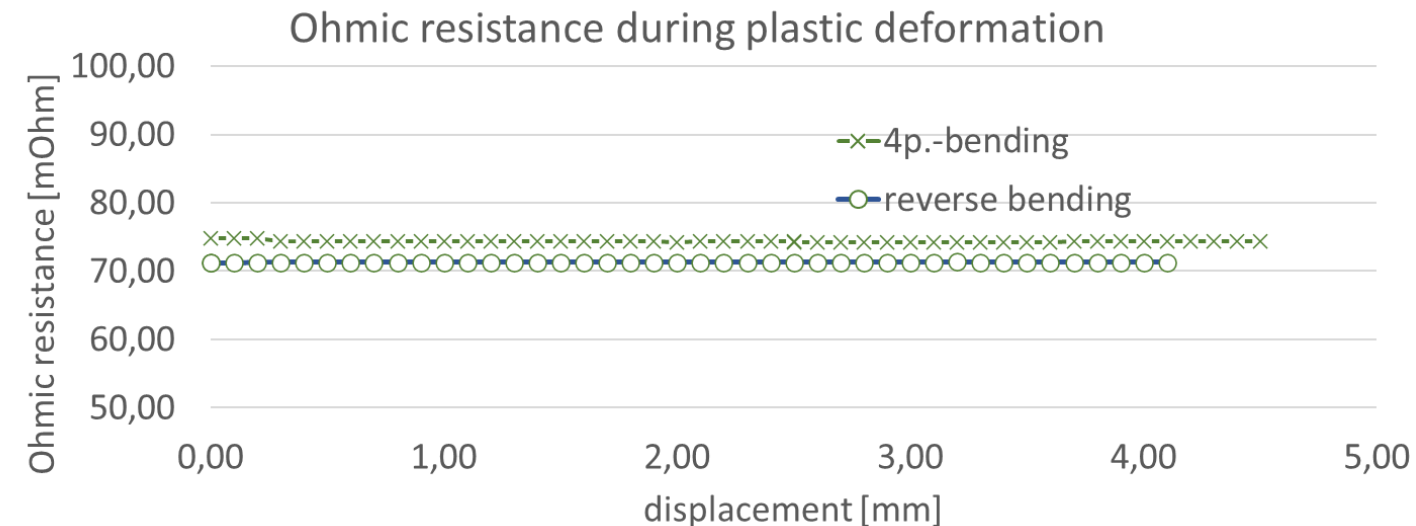


Robustness during mechanical testing

4-point-bending



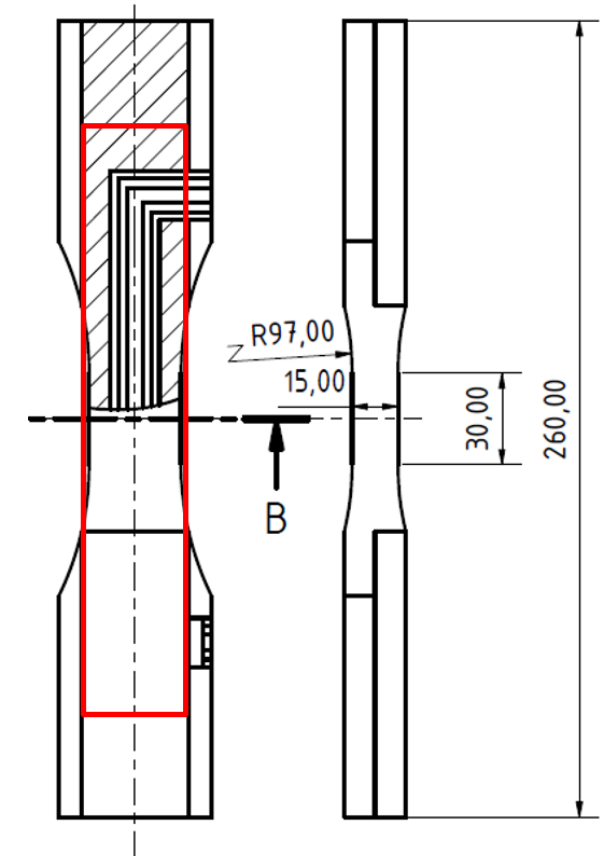
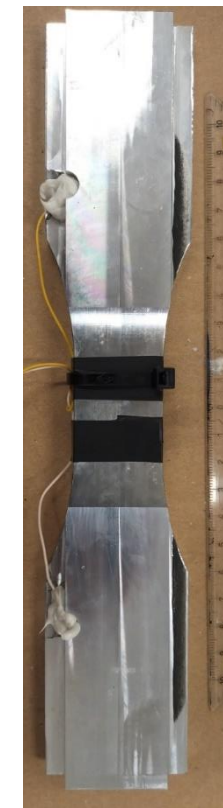
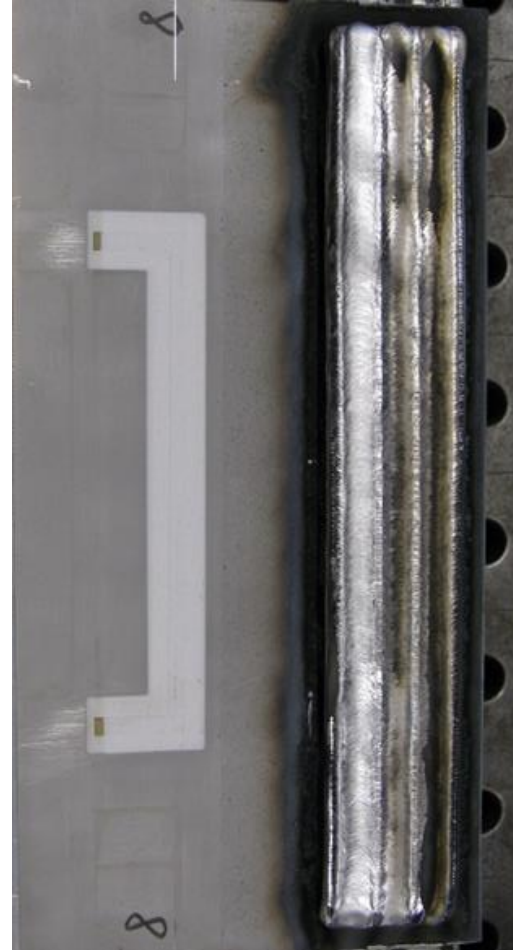
- Samples designed with the stacks positioned in the neutral zone (approx. in the middle to the sample's height)
- Measuring the samples during bending as well as reverse bending (straightening) showing small effects during both procedures running in the plastic regime



Robustness during mechanical testing

Fatigue testing

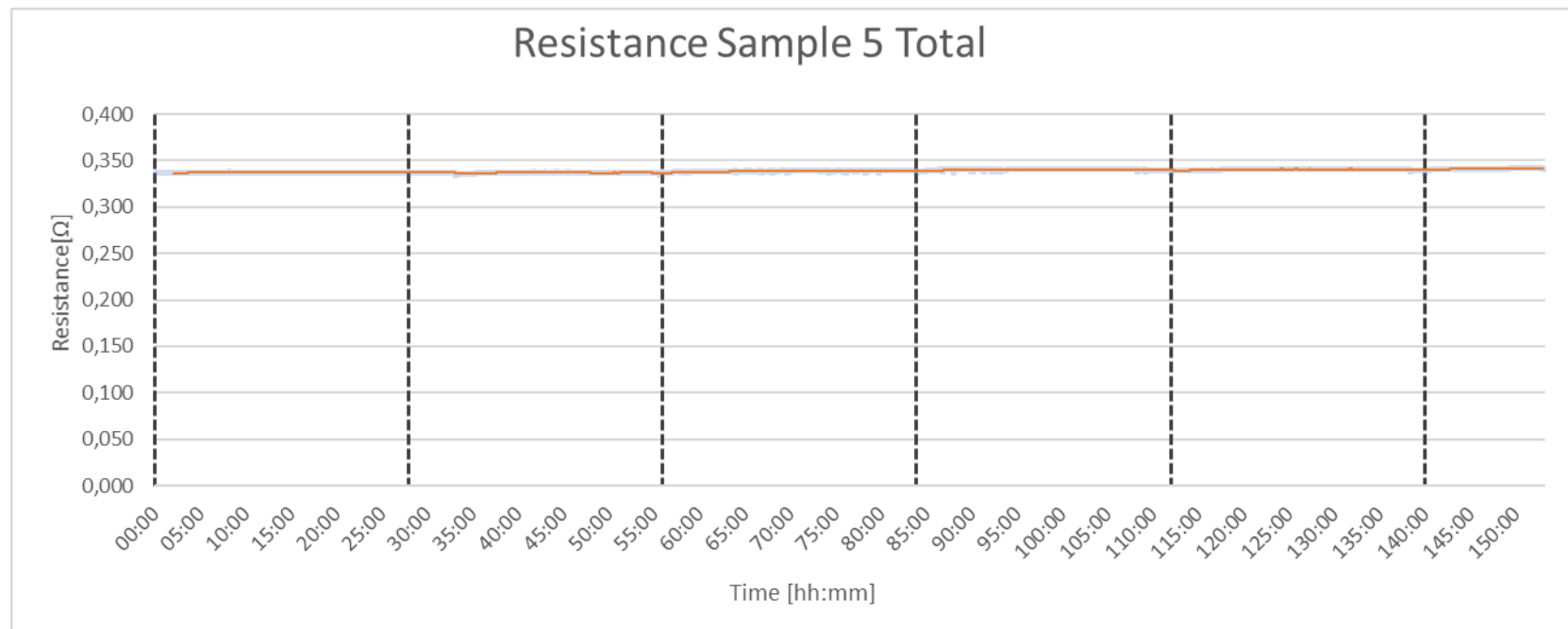
- Fatigue test regime: oscillating tensile load with varying max. load values
- 10 Mio. cycles in 25h duration
- Fatigue test samples subsequently used for static tensile testing



Robustness during mechanical testing

Fatigue testing (1)

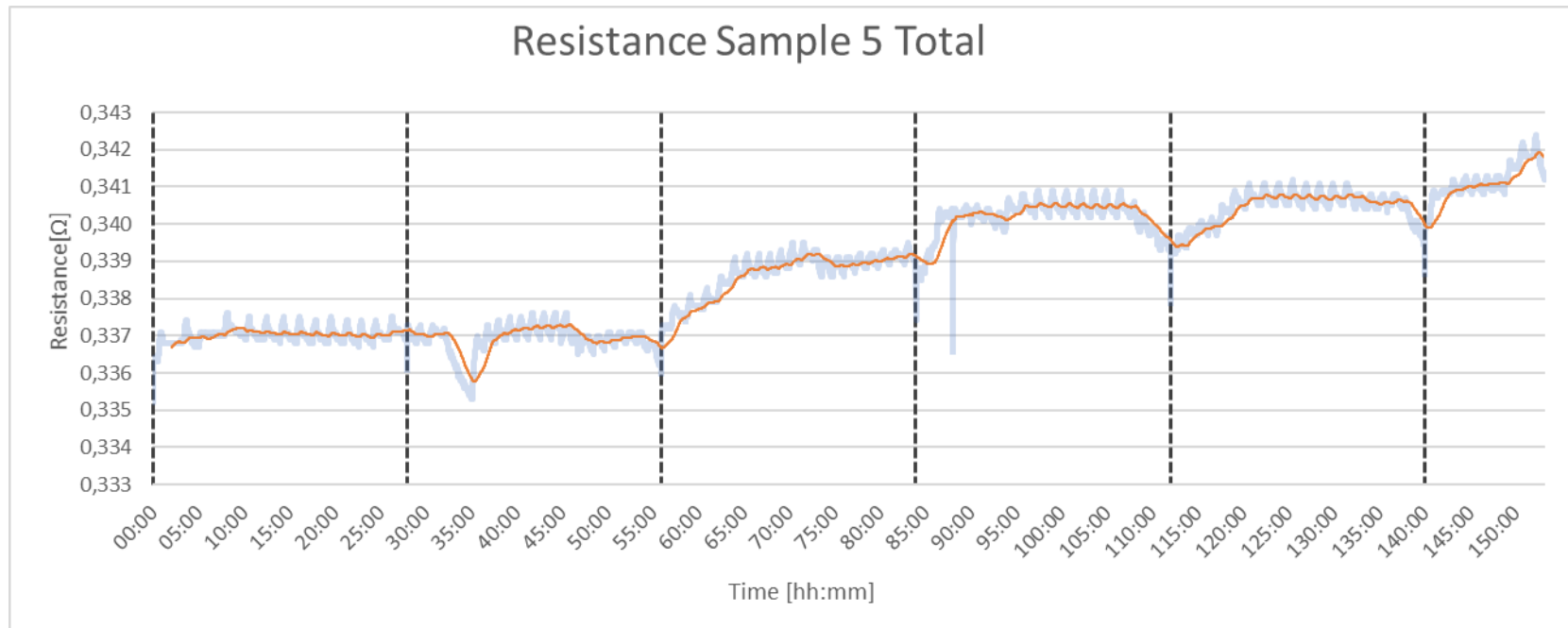
- Test regime: oscillating tensile load with increasing max. values (up to 50% of YS)
- 10 Mio. cycles in 25h duration ► *total values (Ohm) showing nearly no fatigue*



Robustness during mechanical testing

Fatigue testing (2)

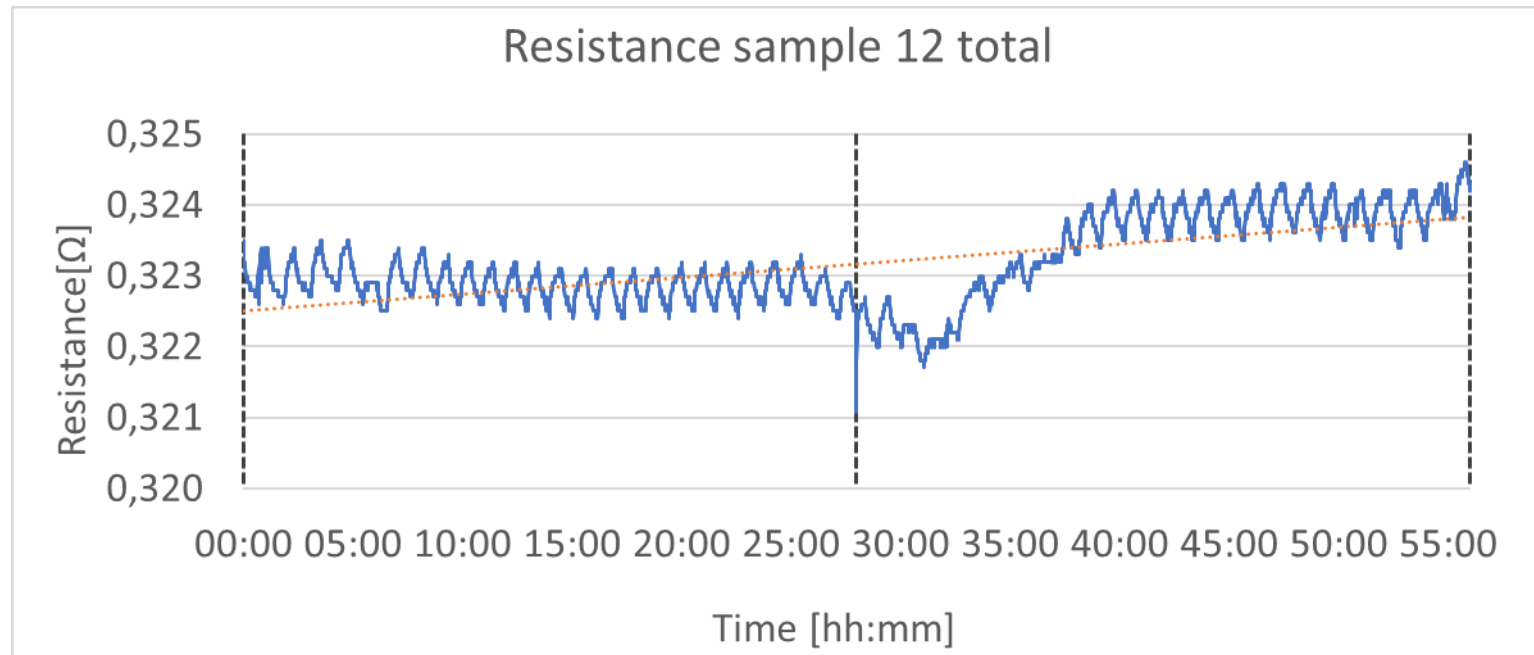
- Test regime: oscillating tensile load with increasing max. values (up to 50% of YS)
- after $>55 \times 10^6$ cycles ▼ *effects from temperature changes & increased loads $<2\%$*



Robustness during mechanical testing

Fatigue testing (3)

- Test regime: oscillating tensile load with increasing max. values
- 20 Mio. cycles in ~55h duration ▼ *effects from temperature changes (Nov. 2021)*

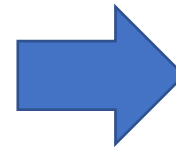
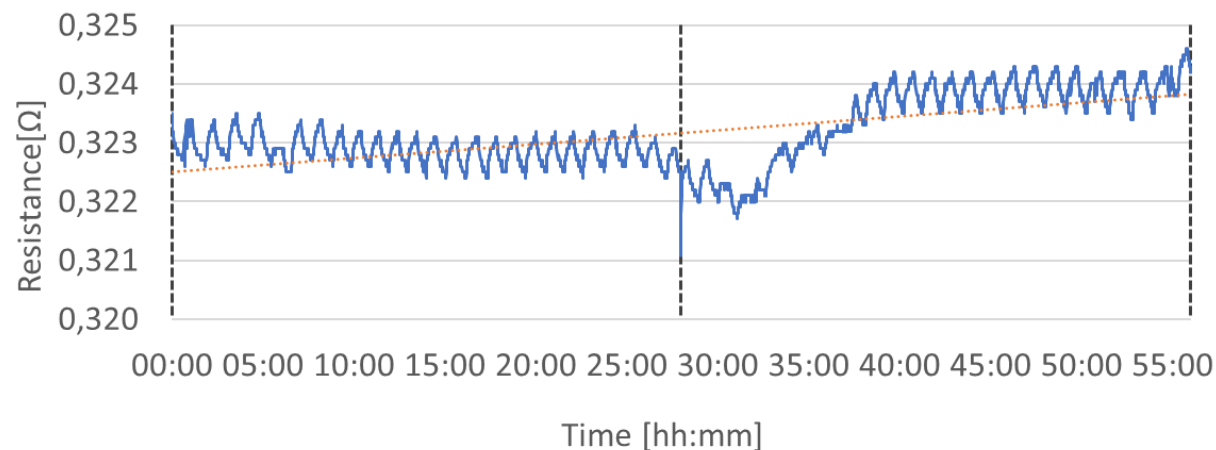


Robustness during mechanical testing

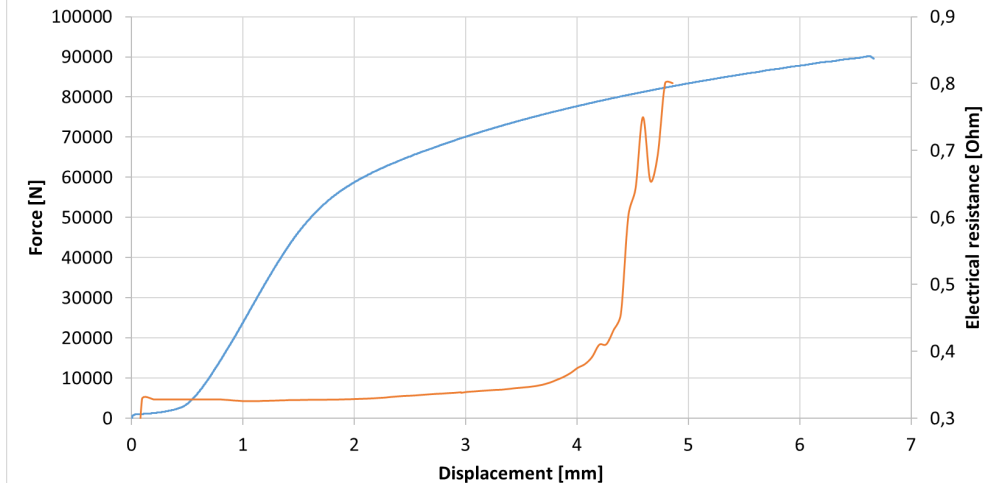
Tensile testing after fatigue testing

- Static tensile testing after 20 Mio. cycles fatigue testing

Resistance sample 12 total



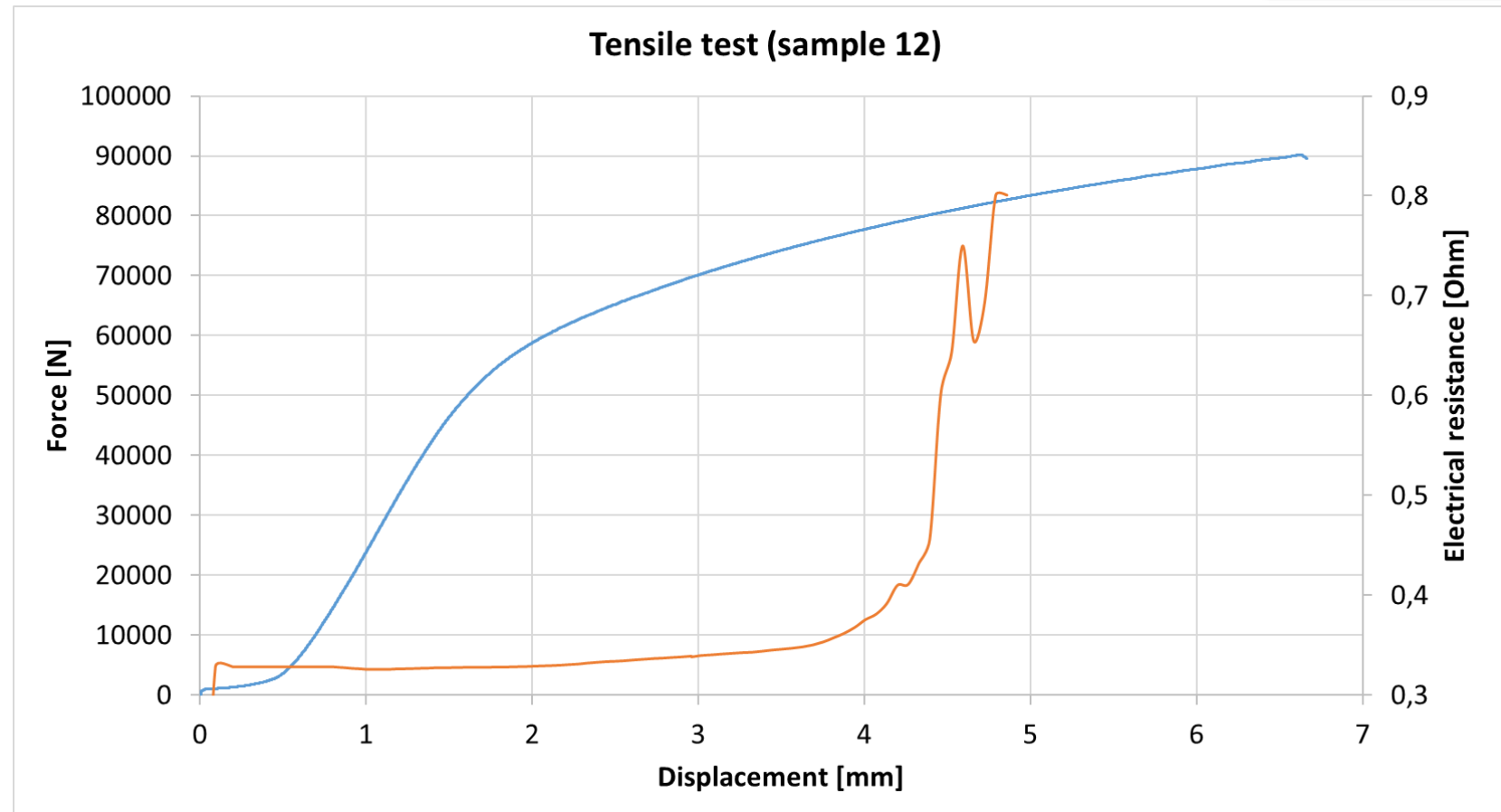
Tensile test (sample 12)



Robustness during mechanical testing

Tensile testing after fatigue testing (2)

Tensile testing showing only small effect of plastic deformation (up to 2mm displacement) on the electrical resistance, obviously showing a deteriorated conductor layer stack beyond 3mm total displacement



Robustness during mechanical testing

Tensile testing after fatigue testing (3)

X-ray testing of sample nr.12 showing
cracks in the ceramic layer stack

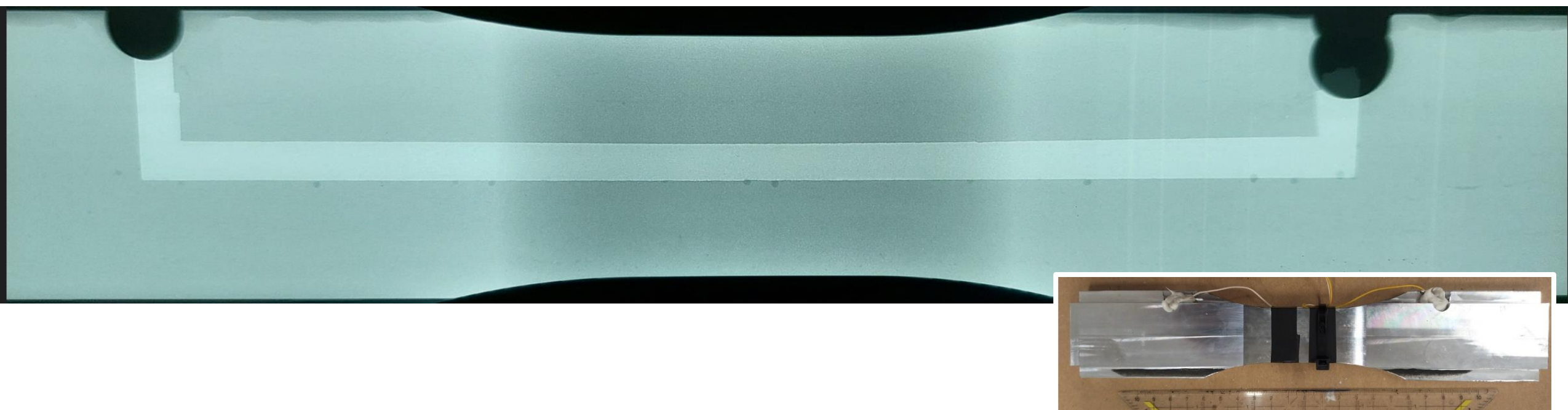


Robustness during mechanical testing

Tensile testing after fatigue testing (4)

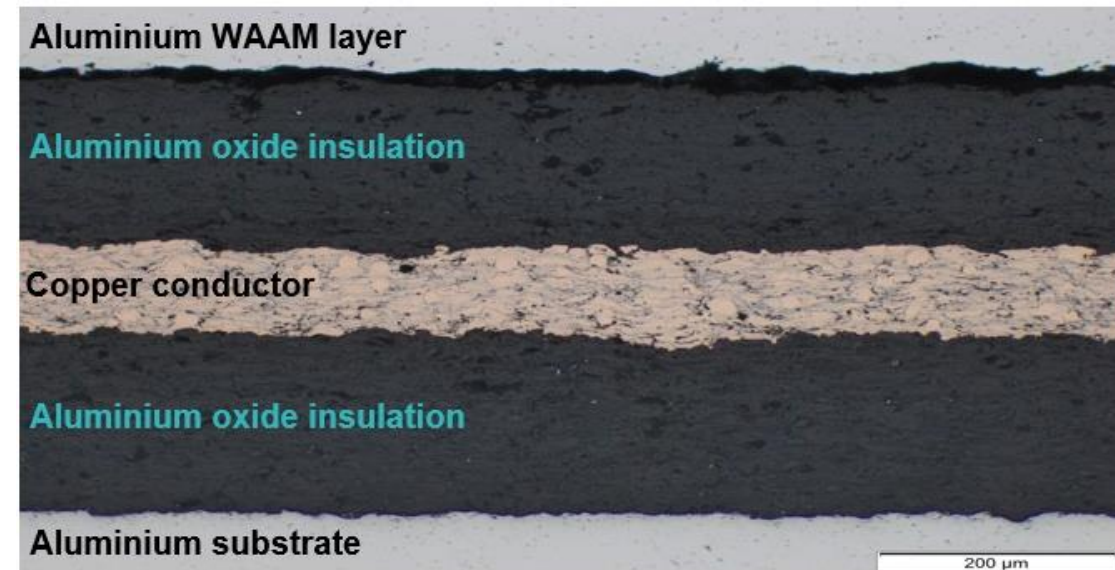
COMPARISON:

X-ray testing of another sample in as built condition



Conclusions & Outlook

- Embedding of insulators & conductors into aluminium substrate by APPD & WAAM successfully shown on 2D specimen level
- Simple specimen design showing good robustness during manufacturing & testing
- Upscaling to larger sizes and 3D geometries ongoing but still challenging
- Postprocessing investigations for increased electrical conductivity ongoing



Next opportunities to meet MULTI-FUN team members



- ▶ Wednesday, 09:00, MAMC 2022, **Andreas Klug & Stefan Karanovic (AVL)** giving their plenary talk about “Additive Manufacturing for Advanced Automotive Measurement Systems - Opportunities & Challenges”
- ▶ MULTI-FUN Speed Tech Forum (Oct 5th 2022, Salzburg) with contributions from **EWF, WAAM3D, RHP, Inphotech, INOCON, DLR, MIGAL & LKR** → see www.MULTI-FUN.eu & register for free: <https://www.eventbrite.co.uk/e/multi-fun-speed-tech-forum-tickets-385582576867>
- ▶ **Stewart Williams (Cranfield University)** giving the keynote lecture “The Contribution of Wire-based Directed Energy Deposition Additive Manufacture to Light Weight Structures and Sustainability” at LKR’s 12. RANSHOFENER LEICHTMETALLTAGE 2022 conference in Salzburg on Oct. 7th 2022 , see <https://www.lmt.ait.ac.at/>
- ▶ **Stewart Williams (WAAM3D) & Eurico Assunção (EWF)** contributing to the Panel “The Future of Standardisation” October 20th 2022 during “IAM” (International Additive Manufacturing) Conference <https://event.asme.org/IAM/Program/Standardization-Panel>



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Acknowledgments



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Thank You!

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